

**AMENDMENTS TO THE CLAIMS:**

Please amend the claims as follows:

1-32. (Cancelled)

33. (New) A circuit substrate comprising:

a substrate including a first surface and a second surface opposite to the first surface;

a first conductor pattern formed on the first surface; and

a second conductor pattern formed on the second surface,

wherein if the circuit substrate is mounted on a second substrate, the second surface is the surface mounted to the second substrate, and

the second surface has larger surface roughness than the first surface.

34. (New) A circuit substrate according to claim 33, further comprising an external terminal formed on the second conductor pattern.

35. (New) A circuit substrate according to claim 34, wherein the external terminal is a ball-shaped solder.

36. (New) A circuit substrate according to claim 33, further comprising a through hole in the substrate connecting the first and second surface.

37. (New) A circuit substrate according to claim 36, further comprising an electrode filled in the through hole.

38. (New) A circuit substrate according to claim 36, further comprising an electrode formed along the through hole.

39. (New) A circuit substrate according to claim 37, wherein the external terminal is connected directly underneath the electrode.

40. (New) A circuit substrate according to claim 38, further comprising a solder filled in the through hole.

41. (New) A circuit substrate according to claim 40, wherein the solder has a higher melting point than the external terminal.

42. (New) A circuit substrate according to claim 33, further comprising a dielectric layer formed on at least a portion of the first and/or second conductor patterns; and a third conductor pattern formed on the dielectric layer.